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Improving Adhesive Bonding of Composites Through Surface Characterization: Potential Composite Bond Contamination By Contact Angle Fluids

2013 Technical Review

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Potential Composite Bond Contamination By Contact Angle Fluids

- Motivation and Key Issues
 - Most important step for bonding is SURFACE PREPARATION!!
 - Inspect the surface prior to bonding to ensure proper surface prep
- Objective
 - Develop quality assurance (QA) techniques for surface prep
- Approach
 - Investigate surface preps, process variables and examine effect of measurements on bonding surface

FAA Sponsored Project Information

- Principal Investigators & Researchers
 - Brian D. Flinn (PI)
 - Ashley C. Tracey (PhD student, UW-MSE)
 - Jonathan T. Morasch (undergraduate, UW-MSE)
 - Aaron Capps (UW-MSE)
- FAA Technical Monitor
 - David Westlund
- Other FAA Personnel Involved
 - Larry Ilcewicz
- Industry Participation
 - Toray Composites
 - Precision Fabrics, Richmond Aerospace & Airtech International
 - The Boeing Company (Marc Piehl, Kay Blohowiak, Pete VanVoast, Will Grace, Tony Belcher, Liz Castro)

2012-2013 Statement of Work

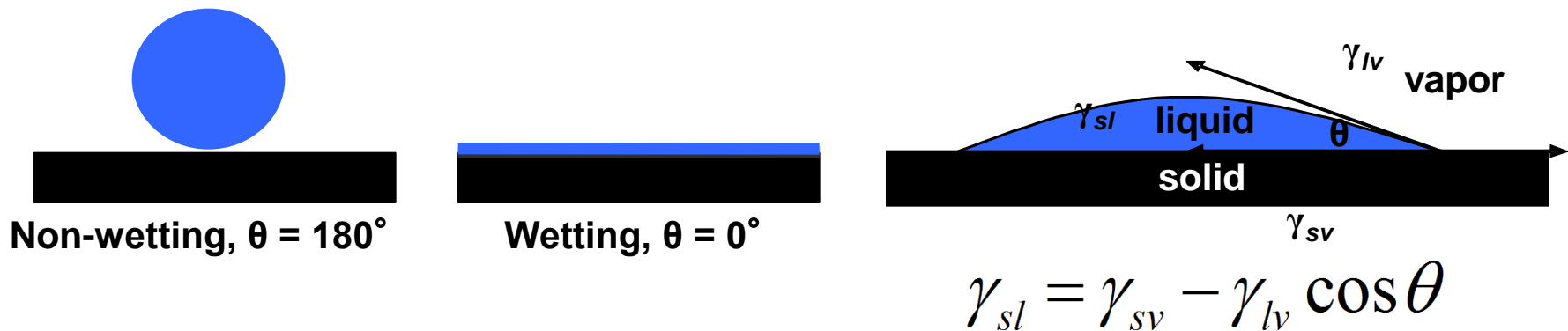
	Surface Characterization/QA Technique			
	Contact Angle		FTIR	
	Goniometer	Surface Analyst	DATR	Diffuse Reflectance
Cure Temp and Dwell Time	✓	✓	In progress	In progress
Peel Ply Prep	✓	✓	✓	✓
Si Contaminants	✓	✓	✓ (Boeing)	
Peel Ply Orientation	✓	✓ No effect	N/A	In progress
Peel Ply + Abrasion	✓		In progress	In progress
Scarfed Surfaces/Repair	In progress	In progress	In progress	In progress
Effect of Measurement on Bonding Surface	✓	TBD	TBD	N/A

✓ = work completed



Surface Energy to Examine Surfaces

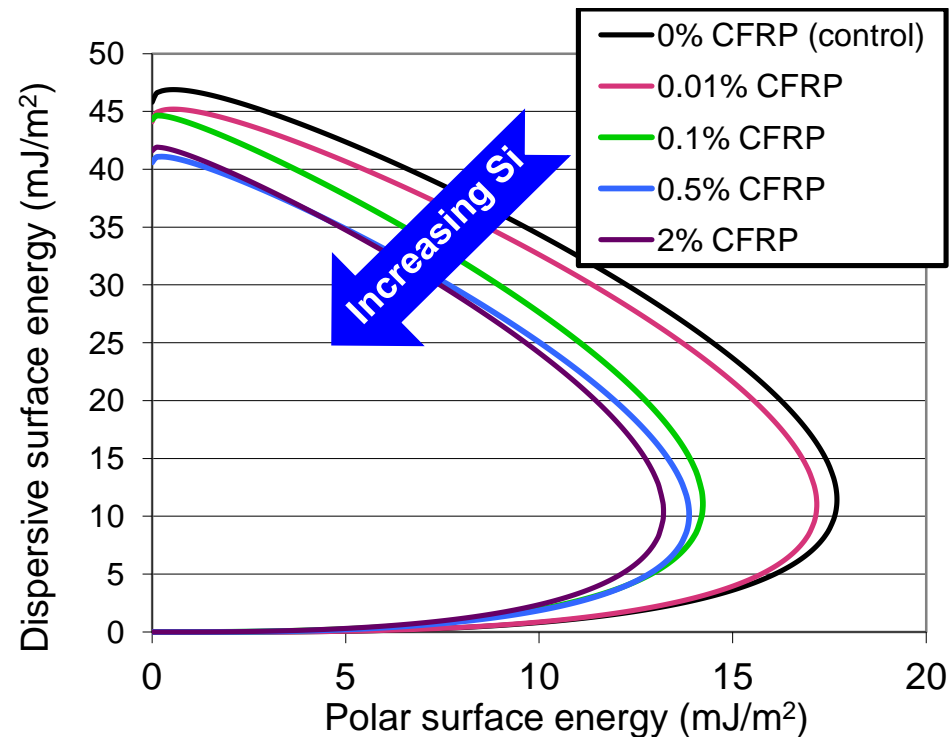
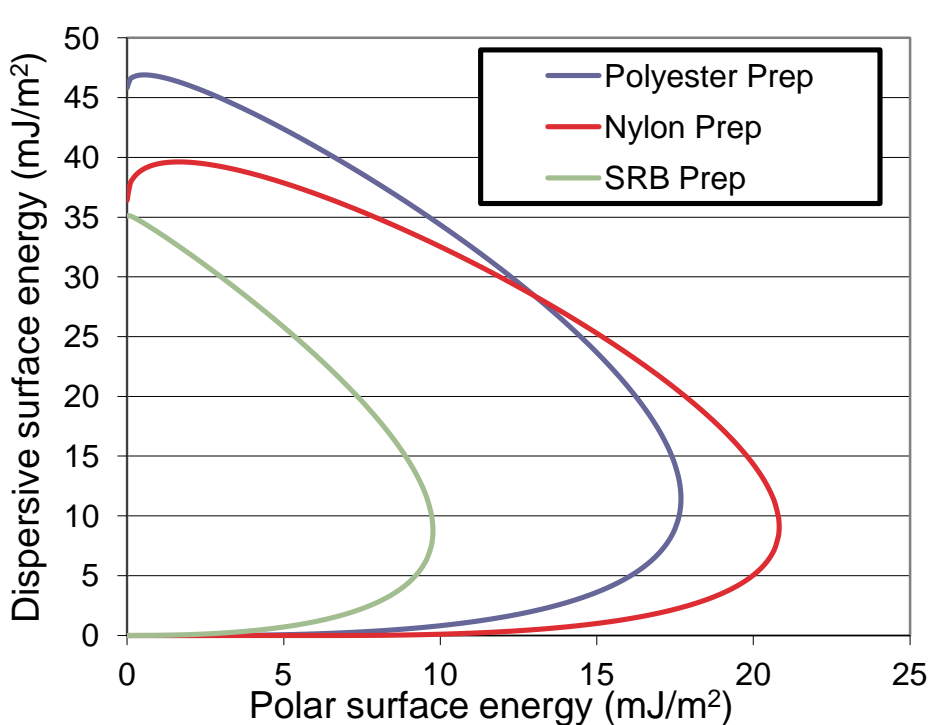
- Adhesive must wet substrate – controlled by surface energy
- Surface energy = measure of energy associated with unsatisfied bonds at the surface [free energy/unit area]
- CAs used to measure surface energy



- Historically: water break test for metal bond QA, not sufficient for composites – esp. peel ply material
 - Need multiple fluids to determine surface energy, wettability envelopes

Contact Angle to Detect Surface Prep

- CA can detect surface prep and silicone contamination
 - Wettability envelopes: 2D representation of surface energy



➤ Need to understand how fluid affects bonding surface

Experimental Overview

Investigate effect of CA fluid application on prepared composite surfaces and resulting bond quality

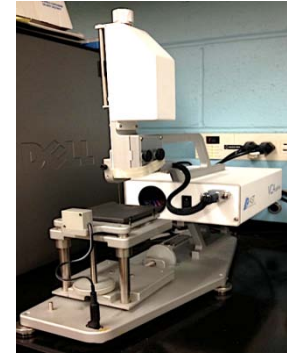
- Apply CA fluid on prepared CFRP surfaces followed by use of one of below methods:
 1. Dry wipe
 2. Acetone wipe
 3. Air dry (in fume hood)
 - Note: amount of fluid applied to surfaces much larger than would typically be exposed to in QA situations
- Fabricate Double Cantilever Beam (DCB) test specimens (bond within 4 hours)
 - Mode I strain energy release rate (G_{IC}) and failure mode

Materials and Process

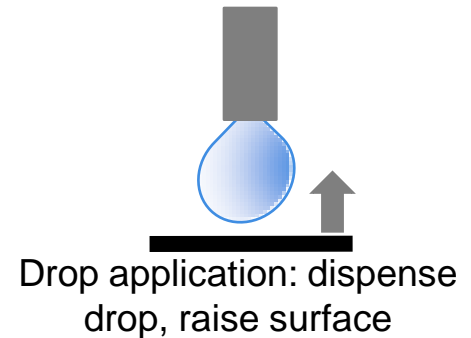
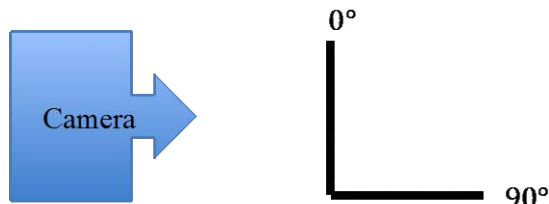
- Toray 3900/T800 unidirectional laminates
 - Autoclave cure (350 ° F, 89 psi)
- Peel ply surface prep
 - Precision Fabric Group 60001 polyester peel ply
- Contact angle fluid application
 - Fluids: DI H₂O, ethylene glycol (EG), glycerol (GLY), diiodomethane (DIM)
 - DuPont Sontara aerospace grade wipes
 - Application and removal of CA fluid

Materials and Process – CA Measurement

- Measure CAs of 1 μL sessile drops from side view using goniometer
 - 10 drops (20 CAs) per fluid
- Fluids: DI H₂O, EG, GLY, DIM
- Measure at 0 or 90° wrt peel ply texture

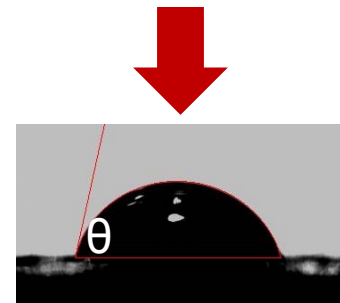


VCA Optima Goniometer



- Calculate CFRP surface energy from CAs

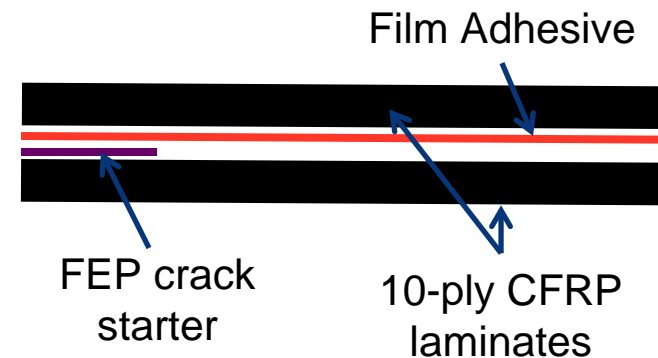
$$\frac{\gamma_{lv}(\cos\theta + 1)}{2\sqrt{\gamma_{lv}^p}} = \sqrt{\gamma_{sv}^d} \left(\sqrt{\frac{\gamma_{lv}^d}{\gamma_{lv}^p}} \right) + \sqrt{\gamma_{sv}^p}$$



Side-view of drop as viewed from goniometer camera

Materials and Process – DCB Testing

- AF 555M film adhesive
 - Aerial weight: 0.050 ± 0.005 lb/ft² [1]
 - Autoclave cure (350 ° C, 89 psi)
 - Bondline thickness: 4.1 - 12.6 mils
- MB 1515-3M film adhesive
 - Aerial weight: 0.05 lb/ft² [2]
 - Autoclave cure (350 ° F, 45 psi)
 - Bondline thickness: 7.4 - 11.8 mils



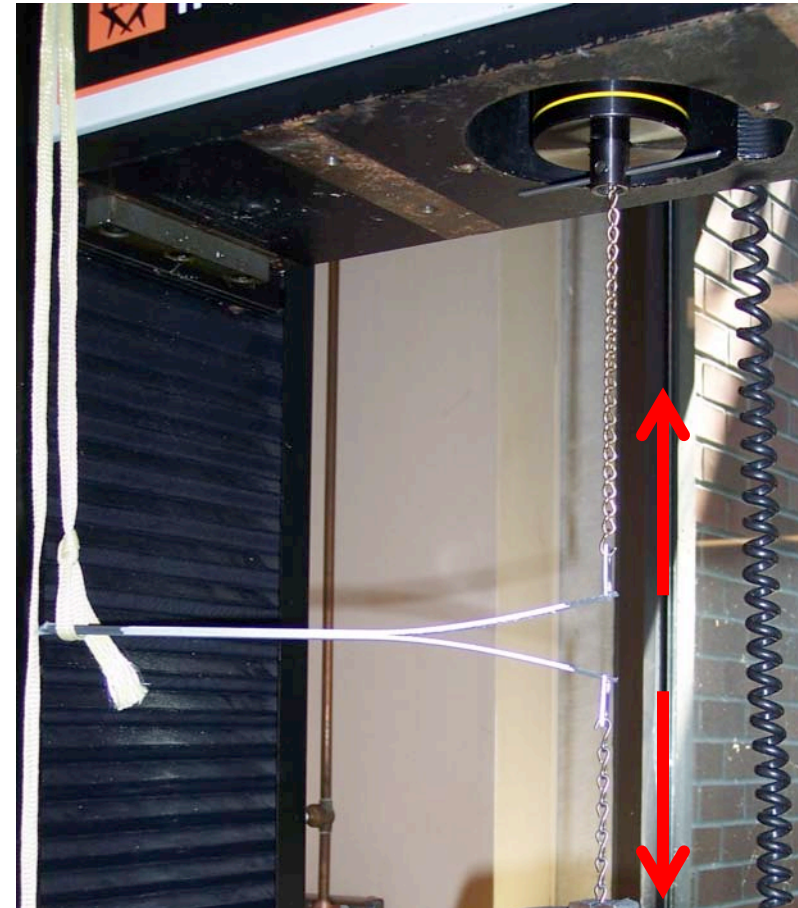
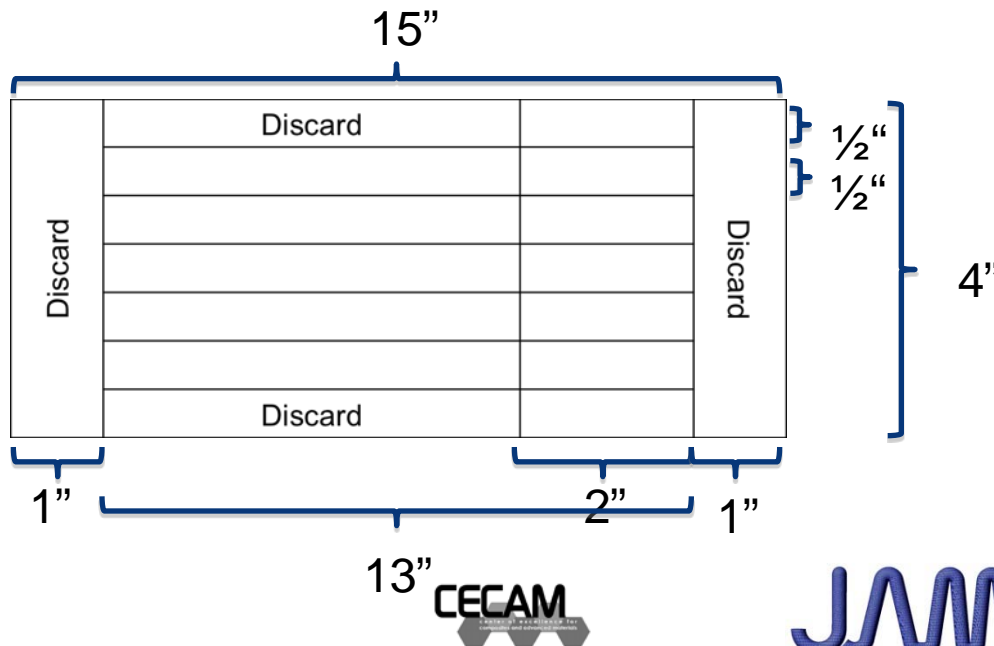
[1] "3M Scotch-Weld Structural Film Adhesive AF 555 Technical Data Sheet." *3M Aerospace and Aircraft*. N.p., Oct 2007. Web. 4 Mar 2013. <<http://www.3m.com/aerospace>>.

[2] "Cytec Metlbond 1515-3 Film Adhesive Technical Data Sheet." *Cytec Engineered Materials*. N.p., 12 Aug 2010. Web. 8 Mar 2013. <<http://www.cytec.com/>>.

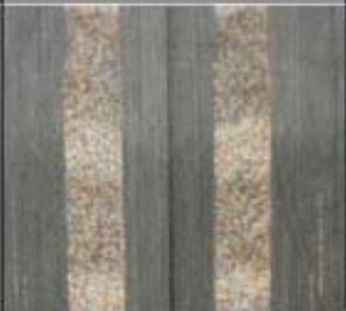



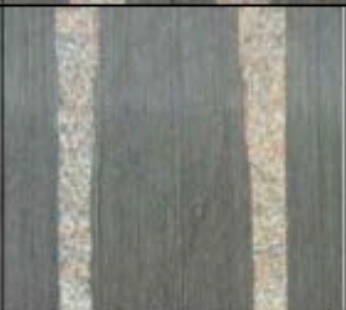

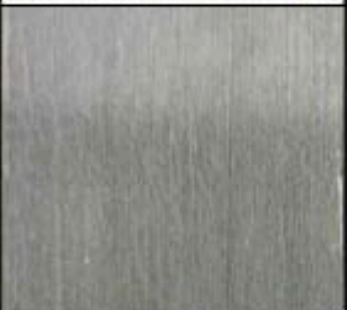

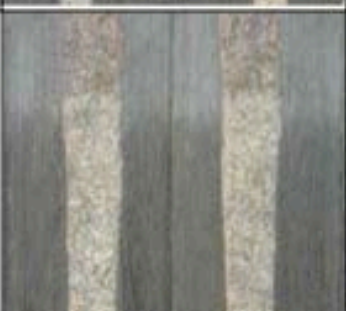
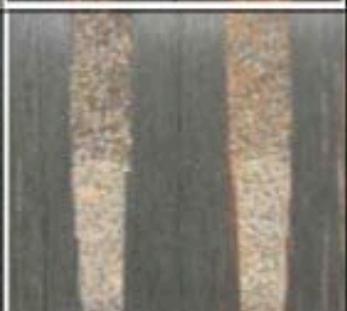
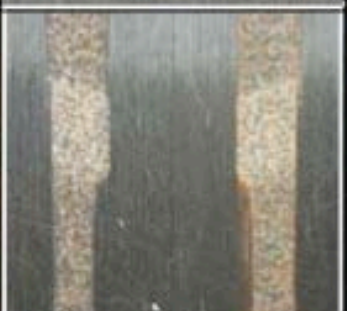

Materials and Process – DCB Testing

- Bonded panels cut into (5) ½” x 13” specimens
- Used area method
 - E: area of curve
 - A: crack length
 - B: specimen width

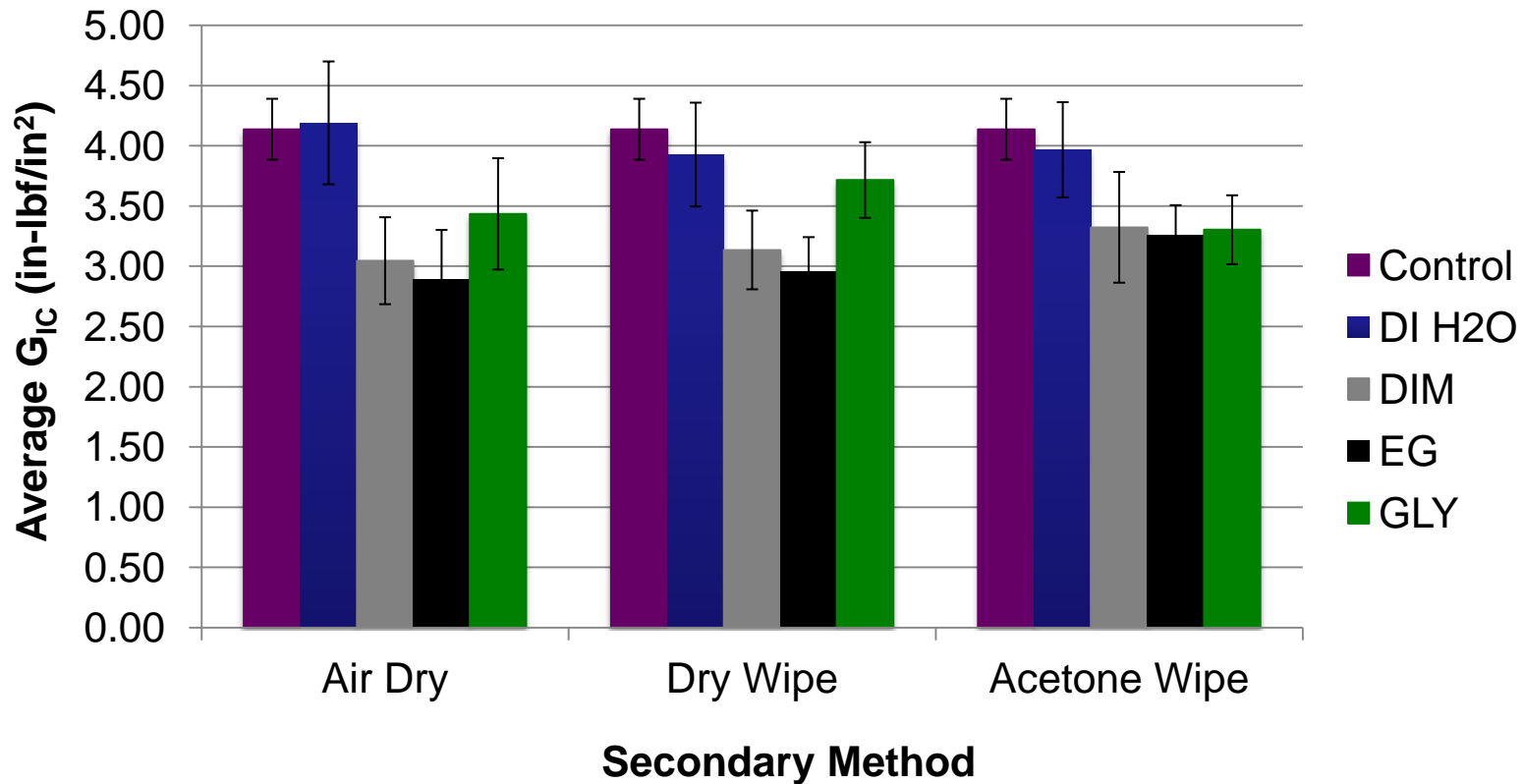
$$G_{IC} = \frac{E}{A \times B}$$



DCB Failure Modes – AF 555M Adhesive

Control	DI H ₂ O	DIM	EG	GLY
Air Dry				
Dry Wipe				
Acetone Wipe				

DCB Mode I Strain Energy Release Rates – AF 555M Adhesive









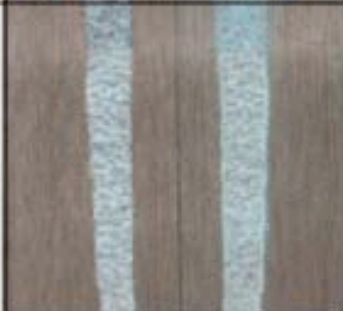





- DI H₂O did not degrade G_{IC}
- DIM and EG decreased G_{IC} 20-30%
- GLY decreased G_{IC} 10-20%

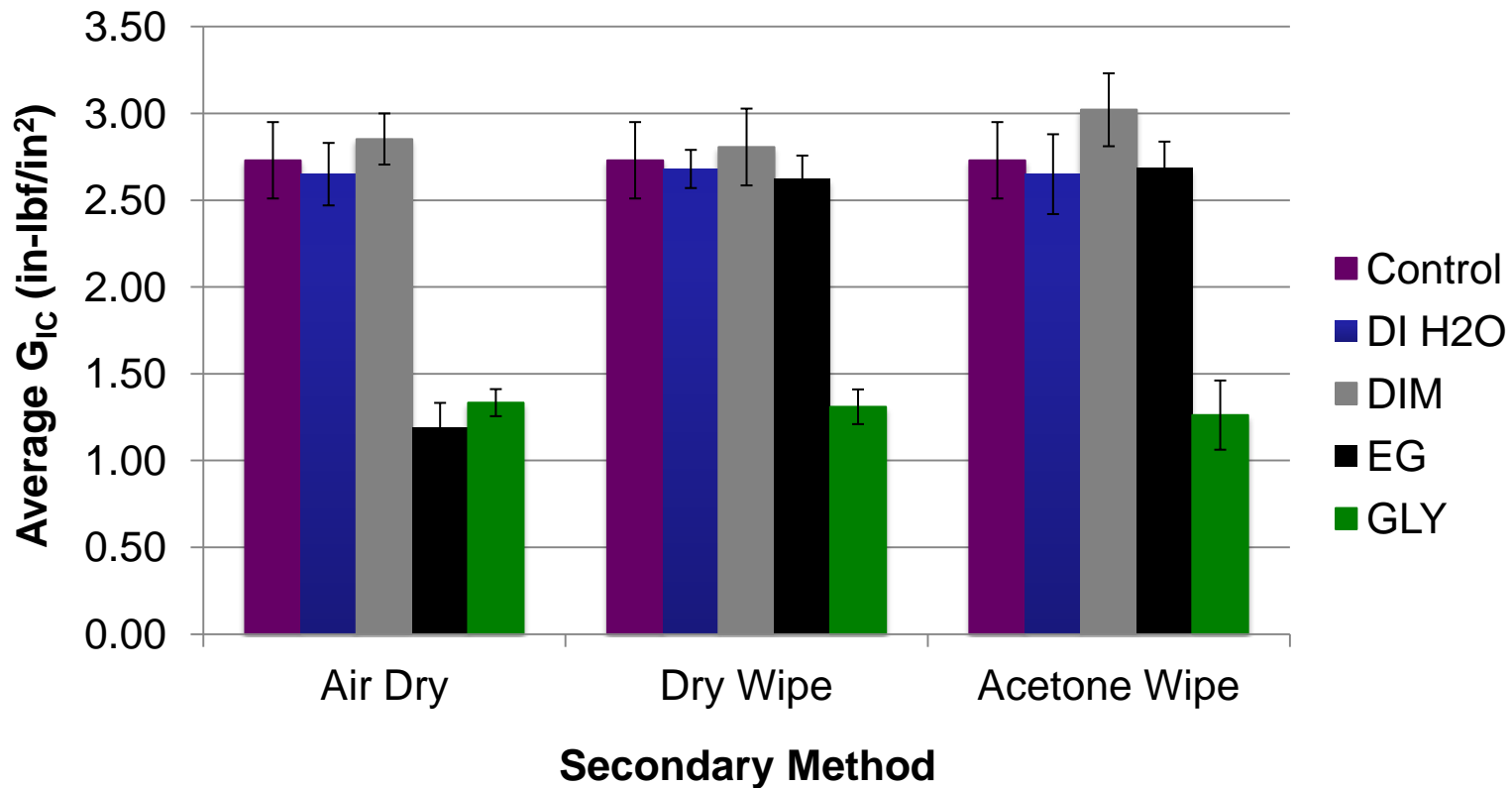
DCB Observations – AF 555M Adhesive

- DI H₂O did not degrade failure mode or G_{IC} compared to control samples
- DIM did not change failure mode but decreased G_{IC} 20-30%
 - Interaction of DIM with substrate and/or adhesive?
- EG decreased G_{IC} 20-30%
 - EG + Air Dry and EG + Dry Wipe mostly interlaminar failure → may explain decrease
 - EG + Acetone Wipe similar failure to control samples
- GLY decreased G_{IC} 20-30%
 - Unexpected as fracture mode mostly cohesive
 - Interaction between GLY and substrate and/or adhesive?

DCB Failure Modes – MB 1515-3M Adhesive

Control	DI H₂O	DIM	EG	GLY
Air Dry				
Dry Wipe				
Acetone Wipe				

DCB Mode I Strain Energy Release Rates – MB 1515-3M Adhesive

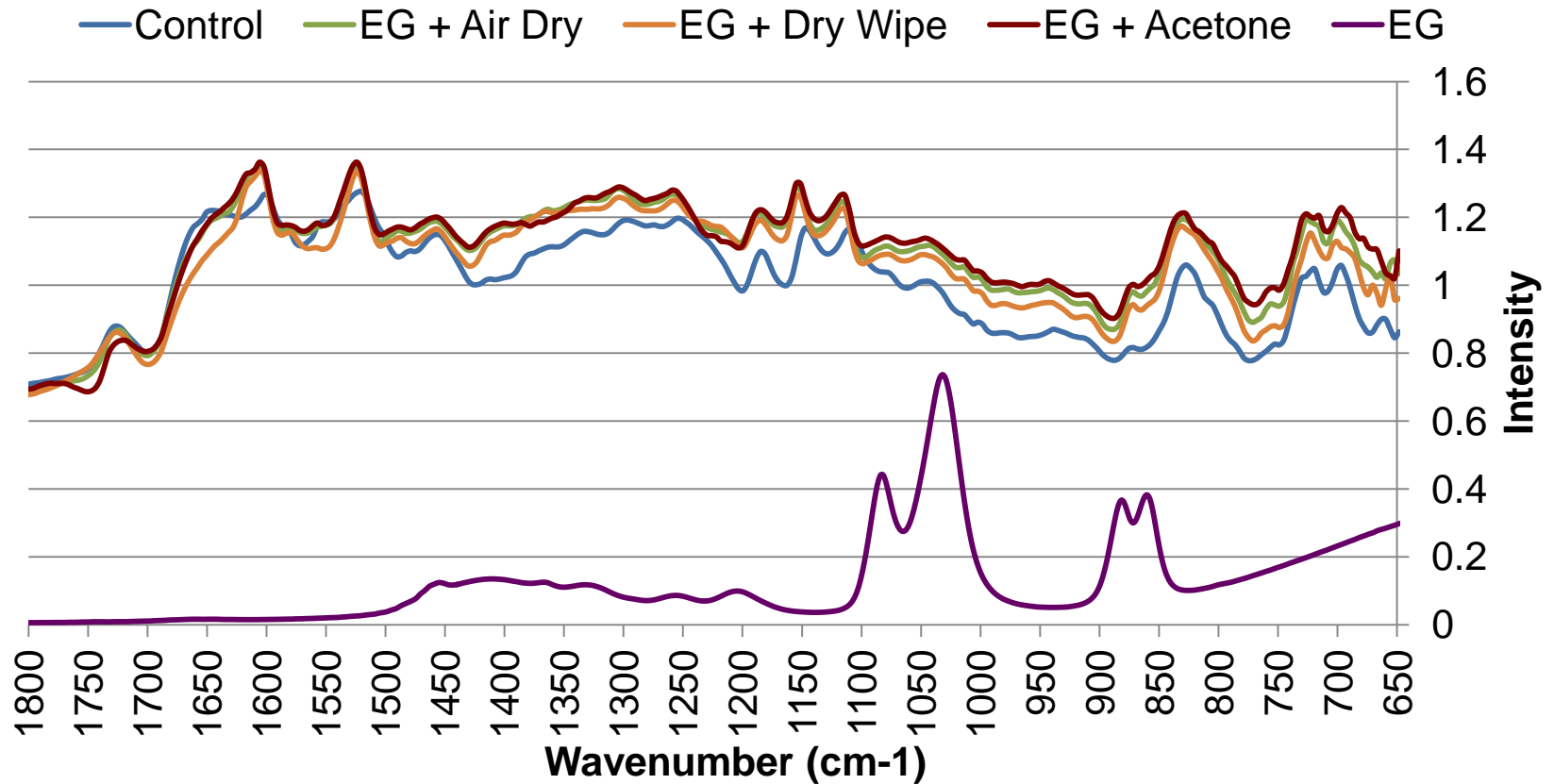


- DI H₂O and DIM did not significantly change G_{IC}
- EG showed variable results
- GLY decreased G_{IC} 50-55%

DCB Observations – MB 1515-3M Adhesive

- DI H₂O and DIM did not degrade failure mode or G_{IC} compared to control samples
- EG showed variable fracture surfaces and G_{IC} measurements
 - FTIR or CA detect differences?
- GLY decreased G_{IC} 50-55%
 - Unexpected as fracture mode mostly cohesive
 - Interaction between GLY and substrate and/or adhesive?

Diffuse Reflectance FTIR Analysis of EG Surfaces



- Slight spectral differences between EG samples but not due to EG on surface

GLY Fracture Surfaces

- GLY fracture surface showed significant bondline porosity compared to control and all other “contaminated” surfaces



Control



GLY + Air Dry



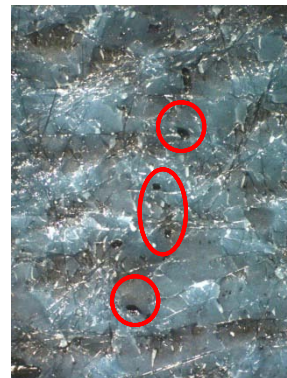
GLY + Dry Wipe



GLY + Acetone Wipe



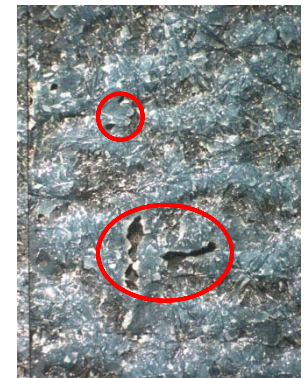
Control



GLY + Air Dry



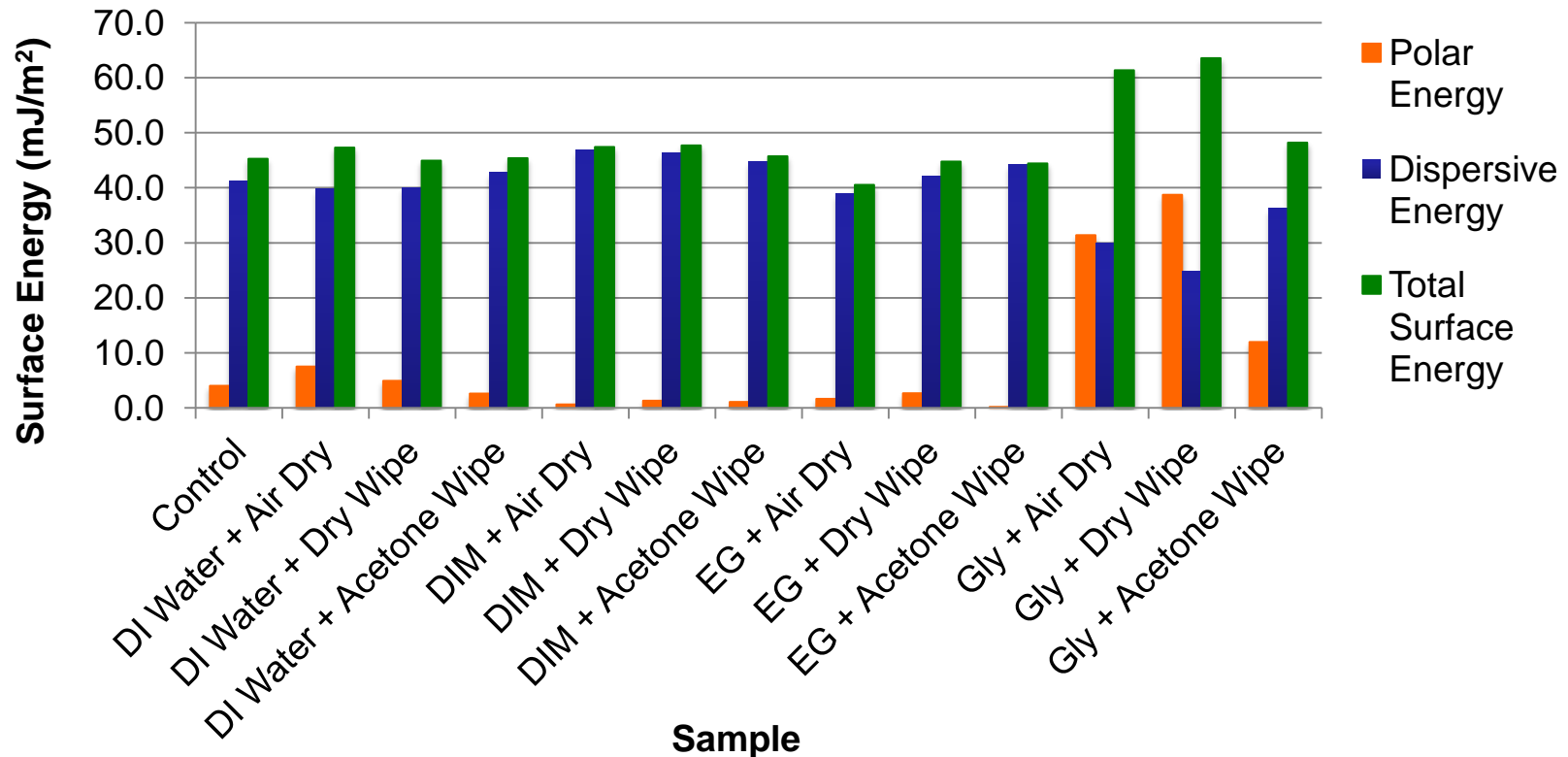
GLY + Dry Wipe



GLY + Acetone Wipe

CA Measurements

- Some CA probe fluids affect G_{IC} and fracture mode \rightarrow CA analysis of “contaminated” surfaces



- DI H₂O, DIM and EG did not significantly change surface energy
- GLY showed largest difference in surface energies
 - GLY + Air Dry and GLY + Dry Wipe samples approaching surface energy of GLY itself ($\gamma^p = 30$ mJ/m², $\gamma^d = 34$ mJ/m²)

Summary

- Contact angle used to measure bonding surfaces → effect of measurement on surface?
- All DCBs showed acceptable failure modes – no adhesion failure
- Some observations of decrease in G_{IC} and change in failure mode
 - CA analysis showed surface energy differences for GLY substrates
 - More research necessary to understand other G_{IC} and failure mode differences
 - Note: amount of fluid applied to bonding surfaces much larger than would typically be exposed to in QA situations

Looking Forward

- Benefit to Aviation
 - Guide development of QA methods for surface prep.
 - Greater confidence in adhesive bonds
- Future needs
 - Application to other composite/surface prep./adhesive systems (repair, paste adhesive, etc.)
 - Model to guide bonding based on characterization, surface prep. and material properties
 - QA methods to ensure proper surface for bonding

Acknowledgements

- FAA, JAMS, AMTAS



- Boeing Company

- Marc Piehl, Kay Blohowiak, Pete VanVoast, Will Grace, Tony Belcher, Liz Castro



- Precision Fabric Group



- Richmond Aircraft Products



- Airtech International

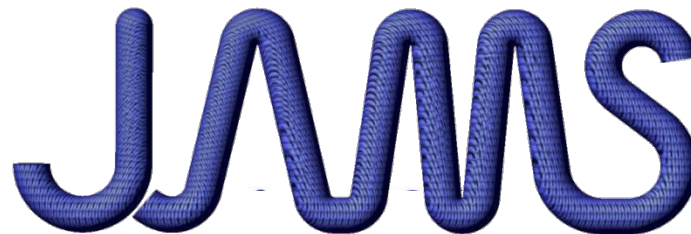


- UW MSE



Thank you!

Questions and comments welcome.



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